L Number	Hits	Search Text	DB	Time stamp
-	1	(electrolytic near4 plating) and (feeder	USPAT;	2003/11/28
_	2007	adj film)	US-PGPUB	12:46
-	3227	(electrolytic near4 plating) and substrate	USPAT; US-PGPUB	2002/11/22 11:07
-	4669	electrolytic near4 plating	USPAT;	2002/11/22
1			US-PGPUB	13:52
-	3142	electrolytic adj plating	USPAT;	2002/11/22 13:52
_	3142	electrolytic adj plating	US-PGPUB USPAT;	2002/11/22
			US-PGPUB	13:52
-	2452	(electrolytic adj plating) and (substrate or semiconductor)	USPAT; US-PGPUB	2002/11/22
_	37	tonami.in.	USPAT;	2002/11/22
			US-PGPUB	14:06
-	3	tonami.in. and Yoshiyuki	USPAT; US-PGPUB	2002/11/22
_	37	tonami.in.	USPAT;	2002/11/22
			US-PGPUB	14:06
_	485	tonami.in.	JPO;	2002/11/22
_		tonami.in. and yoshiyuki	DERWENT JPO;	14:06 2002/11/22
			DERWENT	14:07
-	34	tonami.in. and yoshiyuki	JPO;	2002/11/22
_	2143	216/13.ccls. or 216/18.ccls.	DERWENT USPAT;	14:13 2002/11/22
		210/10:0022: 01 210/10:0013:	US-PGPUB;	14:15
			EPO; JPO;	
			DERWENT; IBM TDB	
_	23	(216/13.ccls. or 216/18.ccls.) and	USPAT;	2002/11/22
		216/40.ccls.	US-PGPUB;	14:15
			EPO; JPO; DERWENT;	
			IBM TDB	
-	1	((216/13.ccls. or 216/18.ccls.) and	USPAT;	2002/11/22
		216/40.ccls.) and 216/100.ccls.	US-PGPUB; EPO; JPO;	14:16
			DERWENT;	
		l	IBM_TDB	
-	147	(216/13.ccls. or 216/18.ccls.) and 205/\$.ccls.	USPAT; US-PGPUB;	2002/11/22 14:16
		200, 4.0013.	EPO; JPO;	17.10
			DERWENT;	
_	0	((216/13.ccls. or 216/18.ccls.) and	IBM_TDB USPAT;	2002/11/22
i	1	205/\$.ccls.) and 216/40.ccls.	US-PGPUB;	14:16
		, , , , , , , , , , , , , , , , , , , ,	EPO; JPO;	
			DERWENT;	
-	11	((216/13.ccls. or 216/18.ccls.) and	IBM_TDB USPAT;	2002/11/22
		205/\$.ccls.) and 216/100.ccls.	US-PGPUB;	14:18
			EPO; JPO; DERWENT;	1
			IBM TDB	
~	35	(205/80.ccls. or 205/123.ccls. or	USPAT;	2002/11/22
		205/125.ccls. or 205/223.ccls.) and taper\$4	US-PGPUB;	14:19
		raharsa	EPO; JPO; DERWENT;	
İ			IBM TDB	
-	1	((205/80.ccls. or 205/123.ccls. or 205/125.ccls. or 205/223.ccls.) and	USPAT; US-PGPUB;	2002/11/22 15:37
		taper\$4) and lift-off	EPO; JPO;	10.07
			DERWENT;	
_	118	205/80.ccls.	IBM TDB	2002/11/22
	110	200,00.0018.	USPAT; US-PGPUB	2002/11/22 15:09
-	121	205/169.ccls.	USPAT;	2002/11/22
			US-PGPUB	15:10

-	0	(205/80, 123, 157, "169" and "223").ccls.	USPAT;	2002/11/22
		and (electrolytic adj plating adj	US-PGPUB	15:40
+		electrode)		
-	0	(205/80,123,157,169,223).ccls. and	USPAT;	2002/11/22
		(electrolytic adj plating adj electrode)	US-PGPUB	15:41
-	0	c25d005/\$.ipc. and (electrolytic near4	JPO;	2002/11/22
		plating) and (feeder adj film)	DERWENT	16:46
-	0	c25d05/\$.ipc.	JPO;	2002/11/22
		05,1005/4	DERWENT	16:45
-	18607	c25d005/\$.ipc.	JPO;	2002/11/22
		205300570	DERWENT	16:45
-	0	c25d005/\$.ipc. and (electrolytic near4	JPO; DERWENT	2002/11/22
ì	651	plating) and (feeder adj film) c25d005/\$.ipc. and (electrolytic near4		16:46
-	031	c25d005/\$.ipc. and (electrolytic near4 plating)	JPO; DERWENT	2002/11/22
l_	55	(c25d005/\$.ipc. and (electrolytic near4	JPO;	18:46 2002/11/22
		plating)) and (feed\$2 or electrode or	DERWENT	16:51
		wire\$4 or base) and (cu or copper or ti	DERWENT	10.31
i		or titanium)	ļ	
_	285	(c25d005/\$.ipc. and (electrolytic near4	JPO;	2002/11/22
		plating)) and (feed\$2 or electrode or	DERWENT	17:38
	1	wire\$4 or base or conduct\$4)		
-	28	(c25d005/\$.ipc. and (electrolytic near4	JPO;	2002/11/22
1	1	plating)) and (feed\$2 or electrode or	DERWENT	18:41
		wire\$4 or base or conduct\$4) near7		
		(pattern or mask\$4)		
	3874	(205/\$ or 216/\$).ccls. and (feed\$4 or	USPAT;	2002/11/22
		electrode or wire\$4 or base or conduct\$4)	US-PGPUB	18:20
		near7 (pattern or mask\$4)		
] -	1492	205/\$.ccls. and (feed\$4 or electrode or	USPAT;	2002/11/22
1		wire\$4 or base or conduct\$4) near7	US-PGPUB	18:24
		(pattern or mask\$4)		
-	1410	(205/\$.ccls. and (feed\$4 or electrode or	USPAT;	2002/11/22
		wire\$4 or base or conduct\$4) near7	US-PGPUB	18:23
	1297	(pattern or mask\$4)) and @ad<20010117	110 D 2 M -	2000/11/00
-	1297	205/\$.ccls. and (feed\$4 or electrode or	USPAT;	2002/11/22
1 .		wire\$4 or base or conduct\$4) near7 (partial\$4)	US-PGPUB	18:28
l _ i	149	(205/\$.ccls. and (feed\$4 or electrode or	USPAT;	2002/11/22
	149	wire\$4 or base or conduct\$4) near7	US-PGPUB	18:32
		(partial\$4)) and (wire\$4 near7 form\$8)	OS-FGFOB	10.32
_	168	(205/\$.ccls. and (feed\$4 or electrode or	USPAT;	2002/11/22
1		wire\$4 or base or conduct\$4) near7	US-PGPUB	18:34
		(partial\$4)) and (wir\$4 near7 form\$5)	00 10102	1 20101
-	43	(205/\$.ccls. and (feed\$4 or electrode or	USPAT;	2002/11/27
		wire\$4 or base or conduct\$4) near7	US-PGPUB	09:52
}		(partial\$4)) and ((wire or wiring)		
		near7 (formation or pattern or]
		fabrication))		
ļ -	1312	(205/80,123,125,223,157).ccls.	USPAT;	2002/11/22
[US-PGPUB	18:40
-	1868	(216/13,18,40,100).ccls.	USPAT;	2002/11/22
	21.02	//005/00 103 105 003 153	US-PGPUB	18:41
-	3103	((205/80,123,125,223,157).ccls.) or	USPAT;	2002/11/22
1_	1015	((216/13,18,40,100).ccls.) (((205/80,123,125,223,157).ccls.) or	US-PGPUB	18:41
_	1013	((216/13,18,40,100).ccls.)) and (feed\$2	USPAT; US-PGPUB	2002/11/22
		or electrode or wire\$4 or base or	US-PGPUB	10:43
		conduct\$4) near7 (pattern or mask\$4 or		
		partial\$4)		
_	964	((((205/80,123,125,223,157).ccls.) or	USPAT;	2002/11/22
	- 3.	((216/13,18,40,100).ccls.)) and (feed\$2	US-PGPUB	18:44
		or electrode or wire\$4 or base or		
·		conduct\$4) near7 (pattern or mask\$4 or		
		partial\$4)) and @ad<20010117		
-	99	(((((205/80,123,125,223,157).ccls.) or	USPAT;	2002/11/23
		((216/13,18,40,100).ccls.)) and (feed\$2	US-PGPUB	15:04
		or electrode or wire\$4 or base or		
		conduct\$4) near7 (pattern or mask\$4 or		
	İ	partial\$4)) and Gad<20010117) and		-
		(electrolytic near4 plating)		

99 (((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating) 99 (((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating) 1 4866008.pn. USPAT; USPAT; 2002/11, 17:09 103 205/186.ccls. USPAT; 2002/11, 2002/11	/26
conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating) (((((205/80,123,125,223,157).ccls.)) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating) - 1 4866008.pn. USPAT; 2002/11.	/23
Celectrolytic near4 plating)	/23
or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating) - 1 4866008.pn. USPAT; 2002/11, US-PGPUB 17:09 - 103 205/186.ccls. USPAT; 2002/11,	
1 4866008.pn. USPAT; 2002/11,	
	/27
US-PGPUB 09:45	141
- 361 (((((205/123,125,223,157,186).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic\$4 or electrodeposit\$4)	/26
- 99 (((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 US-FGPUB 18:59 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and	/26
[electrolytic near4 plating) ((((((205/123,125,223,157,186).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic\$4 or electrodeposit\$4)) not	/26
(((((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4) and (electrolytic near4 plating) - 270 (205/186,123,125,223,157).ccls. and USPAT; 2002/11. ((feed\$2 or electrode or wire\$4 or base US-FGPUB 10:42	/27
or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117 and ((electrolytic near plating) or electroplating or electrodeposit\$4)	
19 205/186 ccls. and ((feed\$4 or electrode USPAT; 2002/11. or wire\$4 or base or conduct\$4 or seed) US-PGFUB 10:34 near7 (partial\$4 or mask or pattern))	/27
- 3 "2000008247" JPO; 2002/11. DERWENT 10:41	/27
- 22685 h011021/3205.ipc. JPO; 2002/11. DERWENT 10:41	
- 47 h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or	/27
electrodeposit\$4) - 1 04262536.pn. DERWENT 2002/11,	/27
14:29 - 1 "04262536" DERWENT 2002/11.	, -
- 2 "04262536" JPO; 2002/11.	/27
DERWENT 15:10 1 5550068.pn. USPAT; 2002/11. US-PGPUB 15:10	/27

	0	(205/186,123,125,223,157). and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or	USPAT; US-PGPUB	2002/11/27
		mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or		
-	283	electrodeposit\$4) (205/186,123,125,223,157).ccls. and ((feed\$2 or electrode or wire\$4 or base	USPAT; US-PGPUB	2002/11/27 15:56
		or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or		
_	384	electrodeposit\$4) (h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4	JPO; DERWENT	2002/11/27 15:55
		or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or		
-	337	electrodeposit\$4) ((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4	JPO; DERWENT	2002/11/27 15:53
		or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not		
		(h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or		
		partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)		
-	28	(((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or	JPO; DERWENT	2002/11/27 16:18
		partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or		
		electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near		
		plating) or electroplating or electrodeposit\$4))) and ((remove or etch) near7 (feed\$2 or electrode or		
-	1	wire\$4 or base or conduct\$4 or seed)) 5550068.pn.	USPAT;	2002/11/27
_	5707	yoshiyuki.in.	US-PGPUB USPAT;	2003/03/28
-	3	yoshiyuki.in. and tonami	US-PGPUB USPAT; US-PGPUB	10:42 2003/03/28 10:42
-	9026	yoshihiro.in.	USPAT; US-PGPUB	2003/03/28
-	13	yoshihiro.in. and koshido	USPAT; US-PGPUB	2003/03/28 10:44
-	15	(yoshiyuki.in. and tonami) or (yoshihiro.in. and koshido)	USPAT; US-PGPUB	2003/03/28
-	154	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wire\$4 near7 form\$6)	USPAT; US-PGPUB	2003/03/31 16:39
-	1311	205/80.ccls. or 205/123.ccls. or 205/125.ccls. or 205/223.ccls.	USPAT; US-PGPUB; EPO; JPO;	2003/03/31 18:09
	1	5550068.pn.	DERWENT; IBM_TDB USPAT;	2003/07/11
	2	"06260482"	US-PGPUB JPO;	14:24 2003/07/11
1	20		DERWENT JPO;	17:42 2003/07/11
	20	(438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)	DERWENT	17:50

			Y	T
_	20	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and	JPO; DERWENT	2003/07/11 17:50
-	509	@ad<20000117 (438/727,643,648,653).ccls. and	USPAT; US-PGPUB	2003/07/11 17:49
	_	(diffusion near3 prevent\$4)		
-	0	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and	JPO; DERWENT	2003/07/11 17:50
		@ad<20000117	TTODAM.	2003/07/11
_	320	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and	USPAT; US-PGPUB	17:50
	000	@ad<20000117	USPAT;	2003/07/11
-	223	(((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and	US-PGPUB	17:50
	0	(4/438/737 643 648 653) ggls and	JPO;	2003/07/11
-	V	(((438/727,643,648,653).ccls. and	DERWENT	17:51
		(diffusion near3 prevent\$4)) and	DEKWENI	1 1 / . 3 1
		@ad<20000117) and (diffusion near3		
	_	prevent\$4 near3 tungsten)	HCDDM.	2003/07/12
-	9	(((438/727,643,648,653).ccls. and	USPAT;	
		(diffusion near3 prevent\$4)) and	US-PGPUB	10:07
		@ad<20000117) and (diffusion near3		
		prevent\$4 near3 tungsten)	l	0000 (07 (10
	1	5550068.pn.	USPAT;	2003/07/12
1			US-PGPUB	10:07
[-	4974	((electro adj plating) or electroplating)	USPAT;	2003/11/28
		same (gold or au)	US-PGPUB	12:49
-	6001	((electro adj plating) or electroplating)	USPAT;	2003/11/28
		same (line or circuit)	US-PGPUB	12:50
-	1514	(((electro adj plating) or	USPAT;	2003/11/28
1		electroplating) same (gold or au)) and	US-PGPUB	12:49
		(((electro adj plating) or		
		electroplating) same (line or circuit))		0000 (11 (00
-	2803	((electro adj plating) or electroplating)	USPAT;	2003/11/28
	0056	with (gold or au)	US-PGPUB USPAT;	2003/11/28
_	2956	((electro adj plating) or	US-PGPUB	12:53
	471	electroplating) with (line or circuit)	USPAT;	2003/11/28
-	4.1	(((electro adj plating) or electroplating) with (gold or au)) and	US-PGPUB	12:51
		(((electro adj plating) or	00 10100	
		electroplating) with (line or circuit))		
_	140	((((electro adj plating) or	USPAT;	2003/11/28
		electroplating) with (gold or au)) and	US-PGPUB	12:52
		(((electro adj plating) or		
		electroplating) with (line or circuit)))		
		and (diffusion or barrier)		
-	2034	((electro adj plating) or electroplating)	USPAT;	2003/11/28
		near7 (gold or au)	US-PGPUB	12:53
-	1966	((electro adj plating) or electroplating)	USPAT;	2003/11/28
		near7 (line or circuit)	US-PGPUB	12:54
-	215	(((electro adj plating) or	USPAT;	2003/11/28
		electroplating) near7 (gold or au)) and	US-PGPUB	15:43
		(((electro adj plating) or		9
1_	365	electroplating) near7 (line or circuit)) (h011021/\$.ipc. or c23c016/\$.ipc.) and	JPO;	2003/11/28
] 303	((electro adj plating) or electroplating)	DERWENT	12:58
		and (gold or au)		
-	101	(h011021/\$.ipc. or c23c016/\$.ipc.) and	JPO;	2003/11/28
		((electro adj plating) or electroplating)	DERWENT	13:19
		and (gold or au) and (line or circuit)		
	23	((h011021/\$.ipc. or c23c016/\$.ipc.) and	JPO;	2003/11/28
1		((electro adj plating) or electroplating)	DERWENT	13:21
1		and (gold or au) and (line or circuit))		
1		and (diffusion or adhesi\$4)		2
-	15	((((electro adj plating) or	USPAT;	2003/11/28
		electroplating) near7 (gold or au)) and	US-PGPUB	15:43
		(((electro adj plating) or		
		electroplating) near7 (line or circuit)))		
L		and (wet near etch\$4)	L	1

- 11 (((((electro adj plating) or electroplating) near7 (gold or au)) and ((slectro adj plating) or electroplating) near7 (line or circuit))) and (wet near etch\$4)) and @ad<20000117	
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